IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

4 y sa 3/1/00

In re the Application of:

Masayuki Yasuda

Serial No.: 09/019,087

Filed: 2/05/98



TIJ-24816

Art Unit: 1765

For: MANUFACTURING METHOD OF SEMICONDUCTOR IC DEVICE

REQUEST FOR RECONSIDERATION

02/23/00

Assistant Commissioner for Patents

Box A.F.

Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R.

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to. Ass't Commissioner for Patents, Box A.F., D.C. 20231 on Fébruary 23, 2000.

William B. Kempler, (Reg. No. 28,228

Applicant requests reconsideration of Claims 1-11 which were rejected by the examiner under 35 U.S.C. Section 103 (A) as being unpatentable over Tsuji '625.

In paragraph 2 of the official action, the examiner states:

"...which is followed by the formation of trenches on said insulating film..." (emphasis added).

On the last line of page 2, the examiner states that:

"...nor does he disclose the trenches having sidewalls."